

## 1. Features

- Typical 1dB bandwidth of 13.9 MHz
- High attenuation
- Single Ended Operation
- Dual In-line Package (DIP)

**RoHS Compliant**

Tested by SGS Testing Korea

## 2. Electrical Specifications

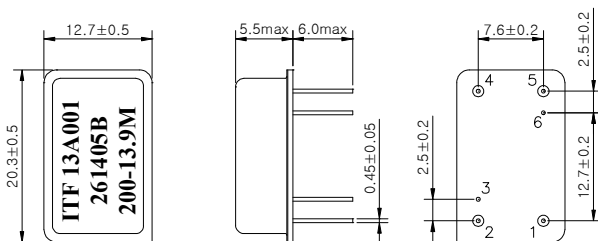
Source and Load Impedance = 50Ω

Room Temperature : +25°C

		Minimum	Typical	Maximum
Center Frequency (fo)	MHz	-	200.0	-
Insertion Loss	dB	-	29.5	31.0
1dB Bandwidth	MHz	13.80	13.95	-
3dB Bandwidth	MHz	-	14.25	-
45dB Bandwidth	MHz	-	15.60	15.75
Amplitude Ripple (Fo±6.7575MHz)	dB	-	0.65	1.2
Group Delay Variation (Fo±6.7575MHz)	nsec	-	35	100
Absolute Delay	usec	-	2.29	2.30
Ultimate Rejection	dB	47	53	-
Temperature Coefficient of Frequency	ppm/°C	-	-18	-
Substrate Material	-		112-LT	

**Input Power : +10dBm**

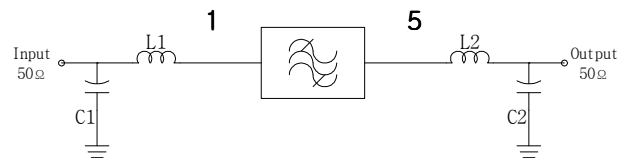
### D2012 Package Dimension



Dimensions shown are nominal in millimeters

Base : Fe(SPCC), Au plating over Ni plated  
Cap : Cu & Cr Alloy, Ni Plated  
Termination : Kovar, Au Plated

### Matching Schematic



**L1 = 27nH, L2 = 22nH, C1 = C2=30pF**

### Pin Configuration

	1	Ground	2,4
Input	1	Ground	2,4
Output	5	Others	Ground

### 3. Typical Performance ( at +25°C )

